

## Features

- $BV_{CEO} > 40V$
- $I_C = 600mA$  Collector Current
- Epitaxial Planar Die Construction
- Ultra-Small Surface Mount Package
- Complementary PNP Type: MMBT2907AT
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

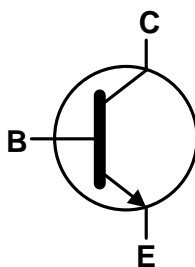
## Mechanical Data

- Case: SOT523
- Case Material: Molded Plastic. "Green" Molding Compound.  
UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin Plated Leads, Solderable per  
MIL-STD-202, Method 208 Ⓔ③
- Weight: 0.002 grams (Approximate)

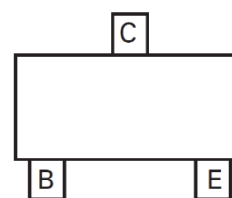
SOT523



Top View



Device Symbol



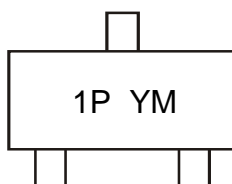
Pin-out Top View

## Ordering Information (Note 4)

Product	Status	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
MMBT2222AT-7-F	Active	AEC-Q101	1P	7	8	3,000

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
  2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

## Marking Information



1P = Product Type Marking Code  
 YM = Date Code Marking  
 Y = Year (ex: D = 2016)  
 M = Month (ex: 9 = September)

### Date Code Key

Year	2016	2017	2018	2019	2020	2021	2022	2023	2024	2025	2026
Code	D	E	F	G	H	I	J	K	L	M	N

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

**Absolute Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	75	V
Collector-Emitter Voltage	V <sub>CEO</sub>	40	V
Emitter-Base Voltage	V <sub>EBO</sub>	6	V
Collector Current	I <sub>C</sub>	600	mA

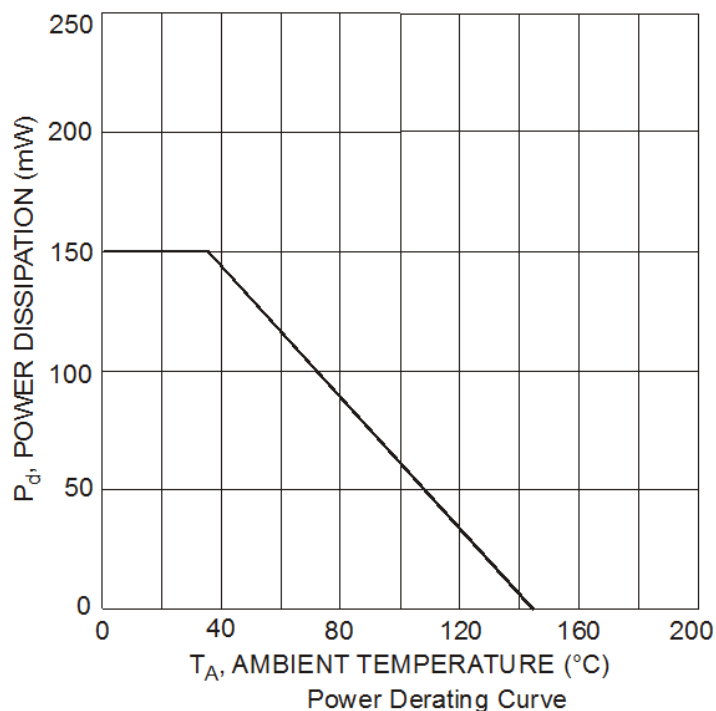
**Thermal Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P <sub>d</sub>	150	mW
Thermal Resistance, Junction to Ambient (Note 5)	R <sub>θJA</sub>	833	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

**ESD Ratings** (Note 6)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

- Notes: 5. For a device mounted with the collector lead on minimum recommended pad layout 1oz copper that is on a single-sided 1.6mm FR-4 PCB; device is measured under still air conditions whilst operating in a steady-state.  
 6. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

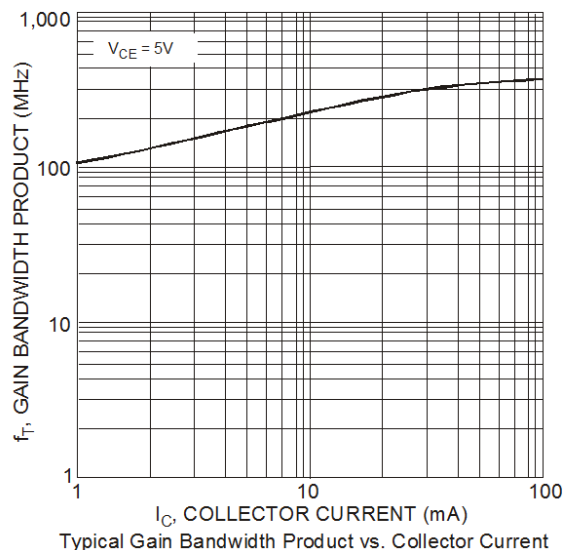
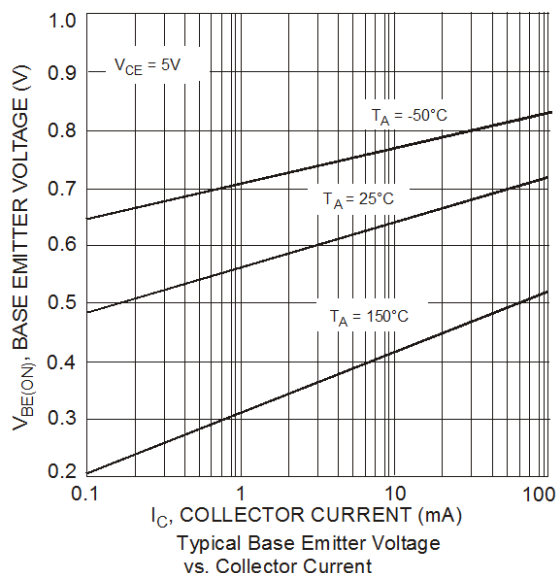
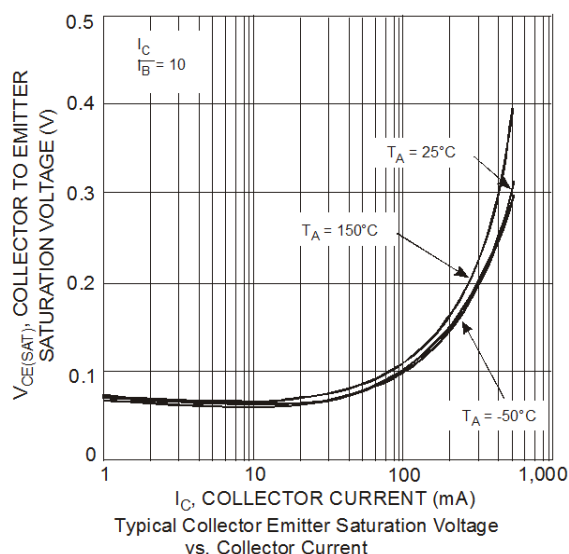
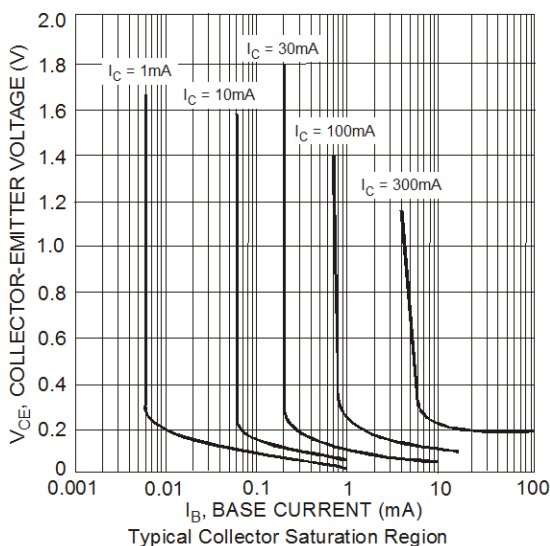
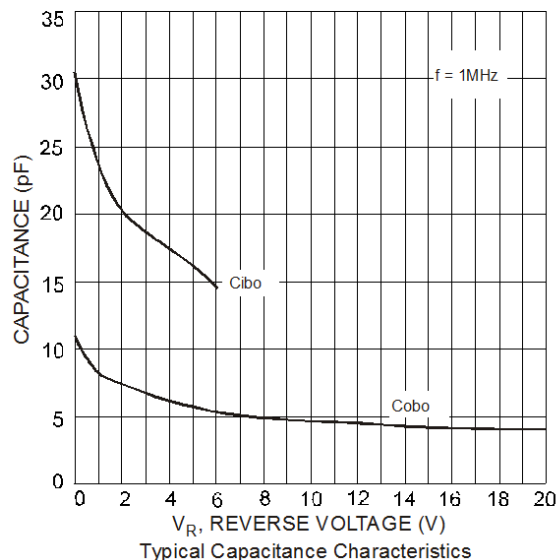
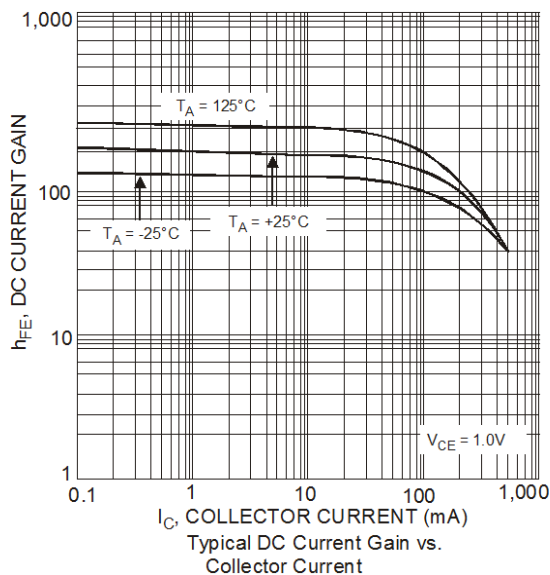
**Thermal Characteristics and Derating Information**


**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)					
Collector-Base Breakdown Voltage	BV <sub>CBO</sub>	75	—	V	I <sub>C</sub> = 10μA, I <sub>E</sub> = 0
Collector-Emitter Breakdown Voltage	BV <sub>CEO</sub>	40	—	V	I <sub>C</sub> = 1mA, I <sub>B</sub> = 0
Emitter-Base Breakdown Voltage	BV <sub>EBO</sub>	6	—	V	I <sub>E</sub> = 10μA, I <sub>C</sub> = 0
Collector Cutoff Current	I <sub>CEX</sub>	—	10	nA	V <sub>CE</sub> = 60V, V <sub>EB(OFF)</sub> = 3V
Base Cutoff Current	I <sub>BL</sub>	—	20	nA	V <sub>CE</sub> = 60V, V <sub>EB(OFF)</sub> = 3V
ON CHARACTERISTICS (Note 7)					
DC Current Gain	h <sub>FE</sub>	35	—	—	I <sub>C</sub> = 100μA, V <sub>CE</sub> = 10V
		50	—		I <sub>C</sub> = 1.0mA, V <sub>CE</sub> = 10V
		75	—		I <sub>C</sub> = 10mA, V <sub>CE</sub> = 10V
		100	300		I <sub>C</sub> = 150mA, V <sub>CE</sub> = 10V
		40	—		I <sub>C</sub> = 500mA, V <sub>CE</sub> = 10V
Collector-Emitter Saturation Voltage	V <sub>CE(SAT)</sub>	—	0.3 1.0	V	I <sub>C</sub> = 150mA, I <sub>B</sub> = 15mA I <sub>C</sub> = 500mA, I <sub>B</sub> = 50mA
Base-Emitter Saturation Voltage	V <sub>BE(SAT)</sub>	0.6 —	1.2 2.0	V	I <sub>C</sub> = 150mA, I <sub>B</sub> = 15mA I <sub>C</sub> = 500mA, I <sub>B</sub> = 50mA
SMALL SIGNAL CHARACTERISTICS					
Output Capacitance	C <sub>obo</sub>	—	8	pF	V <sub>CB</sub> = 10V, f = 1.0MHz, I <sub>E</sub> = 0
Input Capacitance	C <sub>ibo</sub>	—	30	pF	V <sub>EB</sub> = 0.5V, f = 1.0MHz, I <sub>C</sub> = 0
Input Impedance	h <sub>ie</sub>	0.25	1.25	kΩ	V <sub>CE</sub> = 10V, I <sub>C</sub> = 10mA, f = 1.0MHz
Voltage Feedback Ratio	h <sub>re</sub>	—	4.0	x 10 <sup>-4</sup>	
Small Signal Current Gain	h <sub>fe</sub>	75	375	—	
Output Admittance	h <sub>oe</sub>	25	200	μS	
Current Gain-Bandwidth Product	f <sub>T</sub>	300	—	MHz	V <sub>CE</sub> = 20V, I <sub>C</sub> = 20mA, f = 100MHz
SWITCHING CHARACTERISTICS					
Delay Time	t <sub>D</sub>	—	10	ns	V <sub>CC</sub> = 30V, I <sub>C</sub> = 150mA, V <sub>BE(OFF)</sub> = -0.5V, I <sub>B1</sub> = 15mA
Rise Time	t <sub>R</sub>	—	25	ns	V <sub>CC</sub> = 30V, I <sub>C</sub> = 150mA I <sub>B1</sub> = - I <sub>B2</sub> = 15mA
Storage Time	t <sub>S</sub>	—	225	ns	
Fall Time	t <sub>F</sub>	—	60	ns	

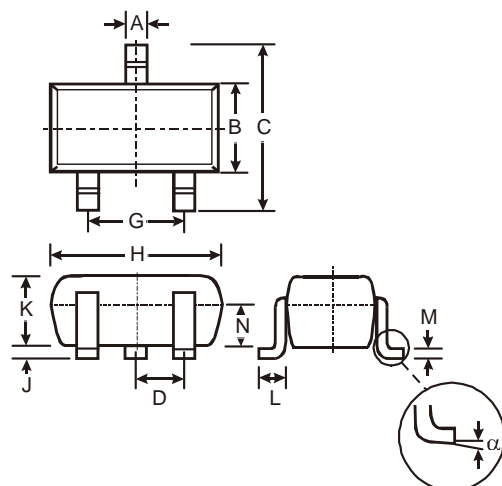
Notes: 7. Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%.

**Typical Electrical Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)



## Package Outline Dimensions

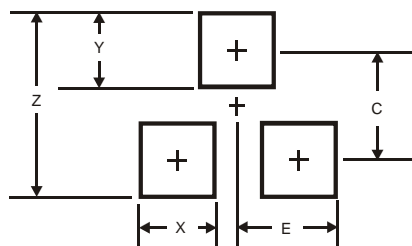
Please see <http://www.diodes.com/package-outlines.html> for the latest version.



SOT523			
Dim	Min	Max	Typ
A	0.15	0.30	0.22
B	0.75	0.85	0.80
C	1.45	1.75	1.60
D	—	—	0.50
G	0.90	1.10	1.00
H	1.50	1.70	1.60
J	0.00	0.10	0.05
K	0.60	0.80	0.75
L	0.10	0.30	0.22
M	0.10	0.20	0.12
N	0.45	0.65	0.50
$\alpha$	0°	8°	—
All Dimensions in mm			

## Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.



Dimensions	Value (in mm)
Z	1.8
X	0.4
Y	0.51
C	1.3
E	0.7

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